



115V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	BV _{DSS} @ T _{J Max}	R _{DS(ON)} Max	I _D Max T _A = +25°C
		65mΩ @ V _{GS} = 10V	4.3A
115V	120V	70mΩ @ V _{GS} = 4.5V	4.5A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

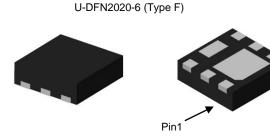
- DC-DC Primary Switch
- Load Switch

Features and Benefits

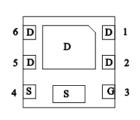
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low On-Resistance
- 100% Unclamped Inductive Switching (UIS) Test in Production –
 Ensures More Reliable and Robust End Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

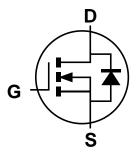
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.0065 grams (Approximate)



Top View Bottom View



Pin Out Bottom View



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Quantity Per Reel		
DMT12H065LFDF-7	U-DFN2020-6 (Type F)	3,000		
DMT12H065LFDF-13	U-DFN2020-6 (Type F)	10,000		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

U-DFN2020-6 (Type F)



96 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: G = 2019) M = Month (ex: 9 = September)

Date Code Key

Year	2019	20	020	2021	2022	20	023	2024	2025	20	026	2027
Code	G		Н	ı	J		K	L	M		N	0
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	Ω	N	D



Marking Information (continued)

U-DFN2020-6 (Type F)



96 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 9 = 2019)

Y = Year (ex: 9 = 2019) W = Week (ex: a = week 27; z represents week 52 and 53)

X = Internal Code (ex: U = Monday)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026	2027
Code	9	0	1	2	3	4	5	6	7

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	115	V
Gate-Source Voltage	V _{GSS}	±12	V	
Continuous Drain Current, V _{GS} = 10V (Note 6)	I _D	4.3 3.4	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	25	Α
Maximum Body Diode Continuous Current (Note 6)		Is	6	Α
Pulsed Body Diode Continuous Current (10µs Pulse, Duty Cycle = 1%	6)	I _{SM}	25	Α
Avalanche Current, L = 0.3mH	I _{AS}	4	Α	
Avalanche Energy, L = 0.3mH	Eas	2.4	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Dawer Dissinction (Note 5)	$T_A = +25^{\circ}C$	C	1.0	W	
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	0.6	VV	
Thermal Resistance, Junction to Ambient (Note 5)		$R_{ heta JA}$	124	°C/W	
Total Power Dissipation (Note 6)	T _A = +25°C	-	1.8	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	P _D	1.2		
Thermal Resistance, Junction to Ambient (Note 6)		$R_{\theta JA}$	69	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	13	C/VV		
Operating and Storage Temperature Range		$T_{J_{i}}T_{STG}$	-55 to +150	°C	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

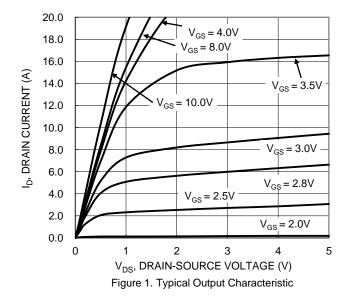


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						•
Drain-Source Breakdown Voltage	BV _{DSS}	115	_	_	V	$V_{GS} = 0V, I_{D} = 10mA$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 92V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_		±100	nA	$V_{GS} = \pm 9.6V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						•
Gate Threshold Voltage	V _{GS(TH)}	0.6		2.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
		_	43	65		$V_{GS} = 10V, I_D = 3A$
Static Drain-Source On-Resistance			54	70	mΩ	$V_{GS} = 4.5V, I_D = 3A$
Static Dialii-Source Off-Resistance	R _{DS(ON)}	_	58	150	11122	$V_{GS} = 3.8V, I_D = 1.0A$
		_	75	350		$V_{GS} = 3V, I_D = 0.5A$
Diode Forward Voltage	V _{SD}	_	8.0	1.3	V	V _{GS} = 0V, I _S = 2.4A
DYNAMIC CHARACTERISTICS (Note 8)				•	•	•
Input Capacitance	C _{iss}	-	252	_	pF	., 50,4,7, 0,4
Output Capacitance	Coss	_	80	_	pF	$V_{DS} = 50V, V_{GS} = 0V,$ - f = 1MHz
Reverse Transfer Capacitance	C _{rss}	_	3	_	pF	1 = 1101112
Gate Resistance	R_{g}	_	6.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge	Q_{g}	_	5.5	_	nC	
Gate-Source Charge	Q _{gs}	_	0.4	_	nC	$V_{DS} = 50V, I_{D} = 4.5A,$
Gate-Drain Charge	Q_{gd}	_	1.7	_	nC	V _{GS} = 10V
Turn-On Delay Time	t _{D(ON)}	_	2.1	_	ns	
Turn-On Rise Time	t _R	_	2	_	ns	$V_{DS} = 50V, R_{L} = 11\Omega$
Turn-Off Delay Time	t _{D(OFF)}	_	10	_	ns	$V_{GS} = 10V, R_{GEN} = 3\Omega$
Turn-Off Fall Time	t _F	_	3.6	_	ns	
Reverse Recovery Time	t _{RR}	_	101	_	ns	1 4 5 4 31/34 000 4 /2
Reverse Recovery Charge	Q_{RR}	_	212	_	nC	$I_F = 4.5A$, di/dt = 300A/ μ s

Notes: Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.





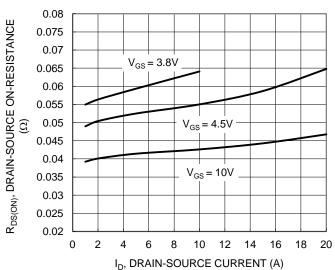
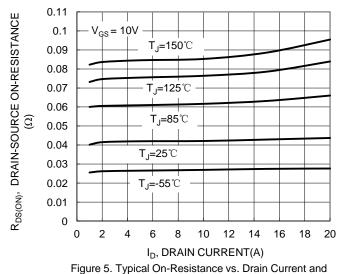
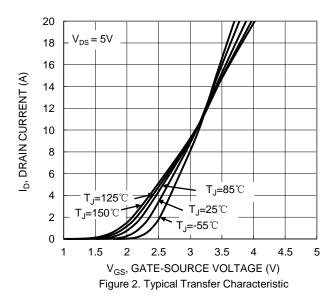
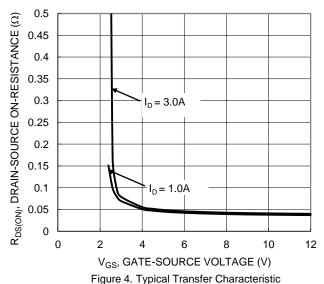


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage



Junction Temperature





R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 2 $V_{GS} = 10V, I_D = 3.02$ 1.8 $V_{GS} = 4.5V, I_{D} = 3.0A$ 1.6 $V_{GS} = 3.8 \text{V}, I_D = 1.0 \text{A}$ 1.4 1.2 1 $V_{GS} = 3.0V, I_D = 0.5A$ 8.0 0.6 -50 -25 0 25 50 75 100 125 150 T_J, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Junction Temperature





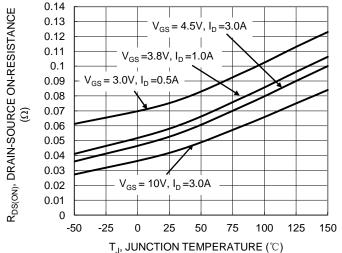
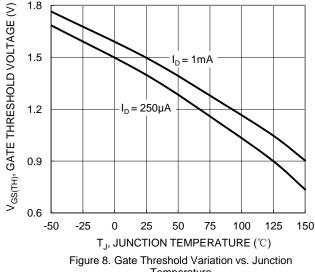
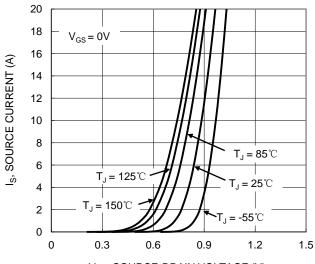


Figure 7. On-Resistance Variation with Junction Temperature



1.8

Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

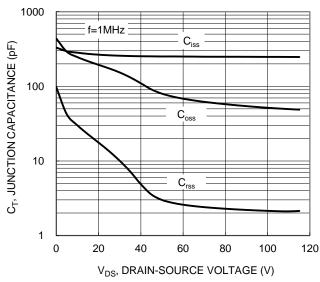


Figure 10. Typical Junction Capacitance

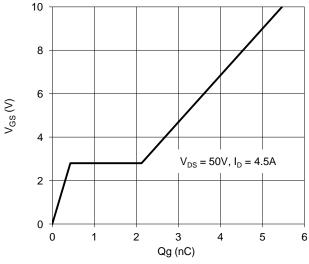
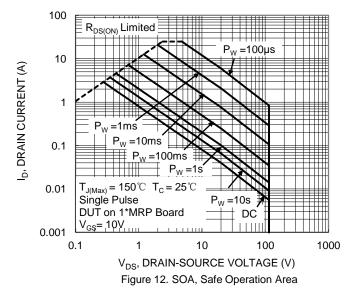


Figure 11. Gate Charge





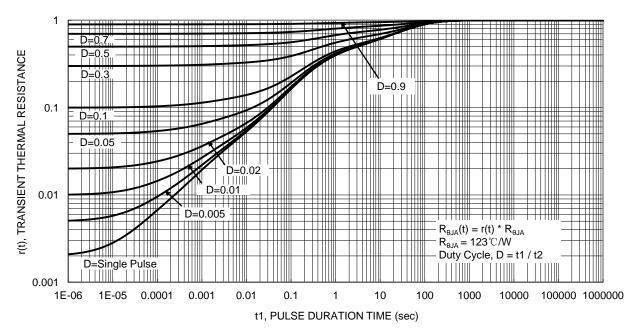


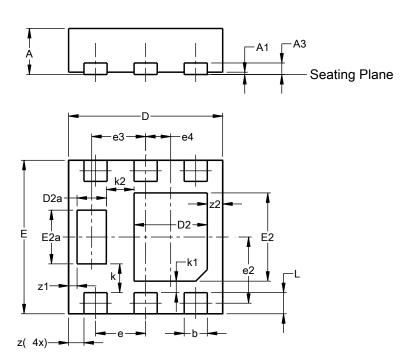
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

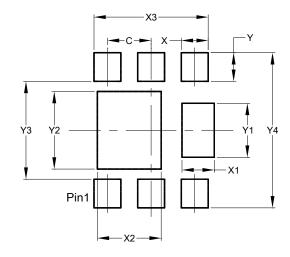


U-DFN2020-6									
	(Type F) Dim Min Max Typ								
Dim	Min	Тур							
Α	0.57	0.63	0.60						
A1	0.00	0.05	0.03						
A3	-	-	0.15						
b	0.25	0.35	0.30						
D	1.95	2.05	2.00						
D2	0.85	1.05	0.95						
D2a	0.33	0.43	0.38						
Е	1.95	2.05	2.00						
E2	1.05	1.25	1.15						
E2a	0.65	0.75	0.70						
е		0.65 BS	С						
e2	().863 BS	SC						
е3		0.70 BS	С						
e4	().325 BS	SC						
k		0.37 BS	С						
k1		0.15 BS	С						
k2		0.36 BS	С						
L	0.225	0.325	0.275						
Z	0.20 BSC								
z 1	0.110 BSC								
z2		0.20 BS	С						
All C	imens	ions in	mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2019, Diodes Incorporated

www.diodes.com

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Diodes Incorporated manufacturer:

Other Similar products are found below:

004419CB 069117AB 1.5KE15A-T 1.5KE15CA-T 1.5KE200A-T 1.5KE20CA-T 1.5KE24A-T 1.5KE250CA-T 1.5KE27CA-T 1.5KE30A-T 1.5KE30CA-T 1.5KE30A-T 1.5KE30CA-T 1.5KE30A-T 1.5KE30CA-T 1.5KE30A-T 1.5KE30CA-T 1.5KE30CA-T 1.5KE30CA-T 1.5KE30CA-T 1.5KE30CA-T 1.5KE30CA-T 1.5KE68CA-T 1.5KE